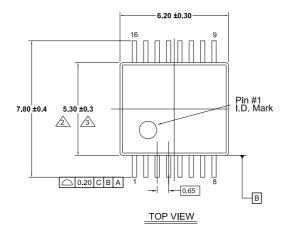
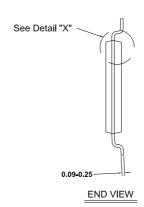
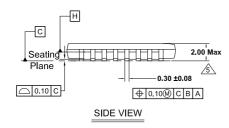
Plastic Packages for Integrated Circuits

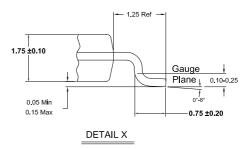
Package Outline Drawing

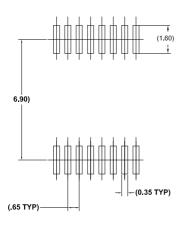
16 Lead Shrink Small Outline Plastic Package (SSOP) Rev 4, 3/2022











Typical Recommended Land Pattern

- Notes:

 (1) Dimension does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 per side.

 (2) Dimension does not include Interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 per side.

 (3) Dimensions are measured at datum plane H.

 (4) Dimensioning and tolerancing per ASME Y14.5M-1994.

 (5) Dimension does not include dambar protrusion. Allowable protrusion shall be 0.80mm total in excess of dimension at maximum material condition. Minimum space between protrusion and adjacent lead is 0.07mm.
- (6) Dimension in () are for reference only.
 (7) Conforms to JEDEC MO-153.